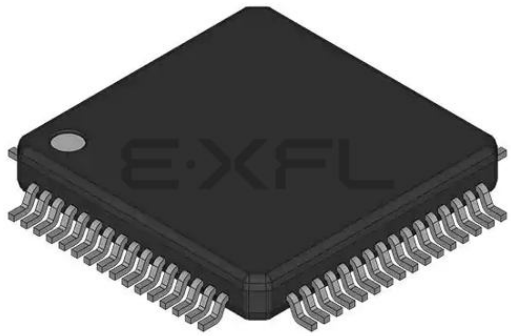

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	20MHz
Connectivity	CSIO, I²C, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 9x12b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/rochester-electronics/mb9af1a2lpmc-g-sne2

Contents

1. Product Lineup

Memory size

Product name		MB9AF1A1L/M/N	MB9AF1A2L/M/N
On-chip Flash memory		64 Kbytes	128 Kbytes
On-chip SRAM	SRAM1	12 Kbytes	16 Kbytes

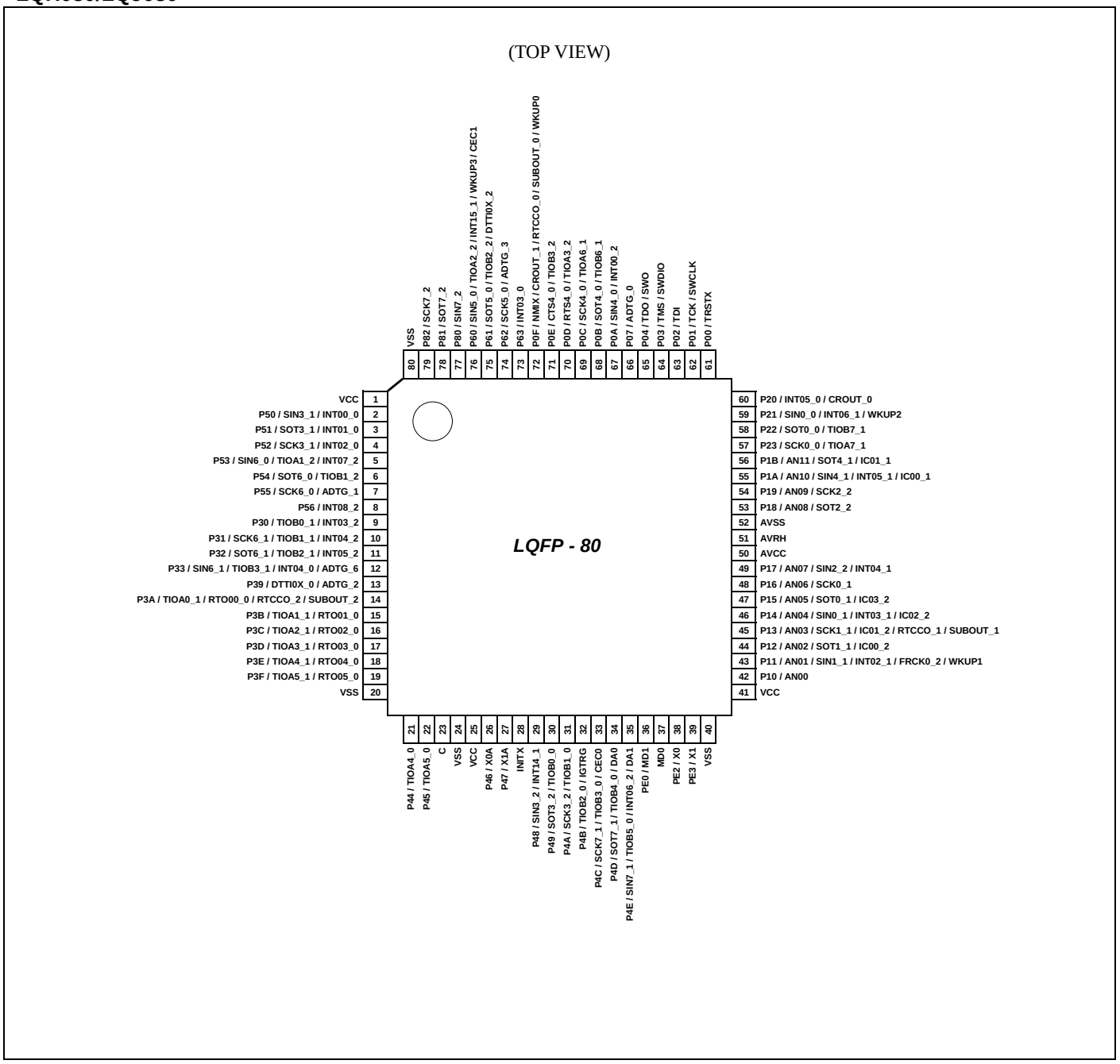
Function

Product name			MB9AF1A1L MB9AF1A2L	MB9AF1A1M MB9AF1A2M	MB9AF1A1N MB9AF1A2N
Pin count			64	80	100
CPU			Cortex-M3		
	Freq.		20 MHz		
Power supply voltage range			1.8 V to 5.5 V		
Multi-function Serial Interface (UART/CSIO/I^{2}C)			8ch. (Max)		
Base Timer (PWC/ Reload timer/PWM/PPG)			8ch. (Max)		
MF-Timer	A/D activation compare	1ch.	1 unit (Max)		
	Input capture	4ch.			
	Free-run timer	3ch.			
	Output compare	6ch.			
	Waveform generator	3ch.			
	PPG (IGBT mode)	3ch.			
HDMI-CEC/ Remote Control Receiver			2ch. (Max)		
Real-time clock (RTC)			1 unit		
Watchdog timer			1ch. (SW) + 1ch. (HW)		
External Interrupts			8 pins (Max)+ NMI × 1	11 pins (Max)+ NMI × 1	16 pins (Max)+ NMI × 1
General-purpose I/O ports			52 pins (Max)	67 pins (Max)	84 pins (Max)
12-bit A/D converter			9ch. (1 unit)	12ch. (1 unit)	16ch. (1 unit)
10-bit D/A converter			2ch. (Max)		
CSV (Clock Super Visor)			Yes		
LVD (Low-Voltage Detector)			2ch.		
Built-in CR	High-speed		4 MHz		
	Low-speed		100 kHz		
Debug Function			SWJ-DP		

Note:

- *All signals of the peripheral function in each product cannot be allocated by limiting the pins of package. It is necessary to use the port relocate function of the I/O port according to your function use. See Electrical Characteristics 12.4 AC Characteristics 12.4.3 Built-in CR Oscillation Characteristics for accuracy of built-in CR.*

LQH080/LQJ080

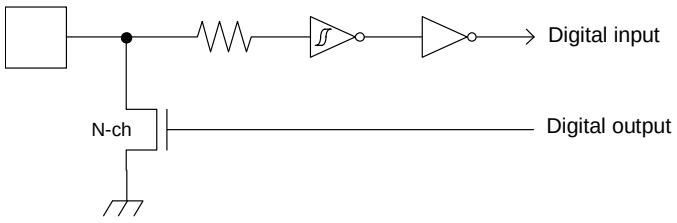
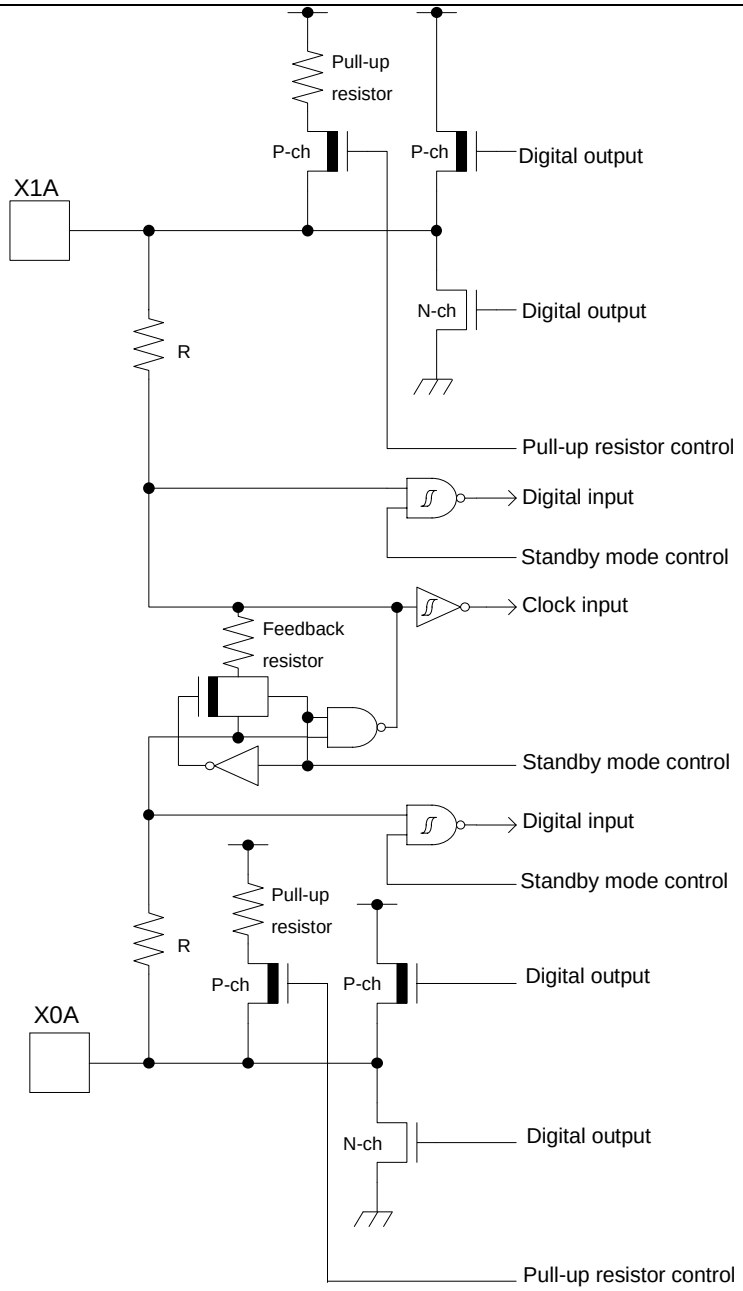


Note:

- *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

Pin No				Pin name	I/O circuit type	Pin state type
LQFP-64	LQFP-80	LQFP-100	QFP-100			
36	44	54	32	P12 AN02 SOT1_1 (SDA1_1) IC00_2	F	J
37	45	55	33	P13 AN03 SCK1_1 (SCL1_1) IC01_2 RTCCO_1 SUBOUT_1	F	J
38	46	56	34	P14 AN04 IC02_2 INT03_1	F	K
-				SIN0_1		
39	47	57	35	P15 AN05 IC03_2	F	J
-				SOT0_1 (SDA0_1)		
-	48	58	36	P16 AN06 SCK0_1 (SCL0_1)	F	J
40	49	59	37	P17 AN07 SIN2_2 INT04_1	F	K
41	50	60	38	AVCC	-	
42	51	61	39	AVRH	-	
43	52	62	40	AVSS	-	
44	53	63	41	P18 AN08 SOT2_2 (SDA2_2)	F	J
45	54	64	42	P19 AN09 SCK2_2 (SCL2_2)	F	J

Pin function	Pin name	Function description	Pin No			
			LQFP-64	LQFP-80	LQFP-100	QFP-100
Multi-function Serial 5	SIN5_0	Multi-function serial interface ch.5 input pin	60	76	96	74
	SIN5_2		-	-	15	93
	SOT5_0 (SDA5_0)	Multi-function serial interface ch.5 output pin. This pin operates as SOT5 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA5 when it is used in an I²C (operation mode 4).	59	75	95	73
	SOT5_2 (SDA5_2)		-	-	16	94
	SCK5_0 (SCL5_0)	Multi-function serial interface ch.5 clock I/O pin. This pin operates as SCK5 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL5 when it is used in an I²C (operation mode 4).	58	74	94	72
	SCK5_2 (SCL5_2)		-	-	17	95
Multi-function Serial 6	SIN6_0	Multi-function serial interface ch.6 input pin	-	5	5	83
	SIN6_1		8	12	12	90
	SOT6_0 (SDA6_0)	Multi-function serial interface ch.6 output pin. This pin operates as SOT6 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA6 when it is used in an I²C (operation mode 4).	-	6	6	84
	SOT6_1 (SDA6_1)		7	11	11	89
	SCK6_0 (SCL6_0)	Multi-function serial interface ch.6 clock I/O pin. This pin operates as SCK6 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL6 when it is used in an I²C (operation mode 4).	-	7	7	85
	SCK6_1 (SCL6_1)		6	10	10	88
Multi-function Serial 7	SIN7_1	Multi-function serial interface ch.7 input pin	27	35	45	23
	SIN7_2		61	77	97	75
	SOT7_1 (SDA7_1)	Multi-function serial interface ch.7 output pin. This pin operates as SOT7 when it is used in a UART/CSIO (operation modes 0 to 2) and as SDA7 when it is used in an I²C (operation mode 4).	26	34	44	22
	SOT7_2 (SDA7_2)		62	78	98	76
	SCK7_1 (SCL7_1)	Multi-function serial interface ch.7 clock I/O pin. This pin operates as SCK7 when it is used in a UART/CSIO (operation modes 0 to 2) and as SCL7 when it is used in an I²C (operation mode 4).	25	33	43	21
	SCK7_2 (SCL7_2)		63	79	99	77

Type	Circuit	Remarks
C		• Open drain output • CMOS level hysteresis input
D		It is possible to select the sub oscillation / GPIO function When the sub oscillation is selected. • Oscillation feedback resistor : Approximately 5 MΩ • With standby mode control When the GPIO is selected. • CMOS level output. • CMOS level hysteresis input • With pull-up resistor control • With standby mode control • Pull-up resistor : Approximately 50 kΩ • I_{OH} = -4 mA, I_{OL} = 4 mA

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
   Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

6.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity

   Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
2. Discharge of Static Electricity

   When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
3. Corrosive Gases, Dust, or Oil

   Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
4. Radiation, Including Cosmic Radiation

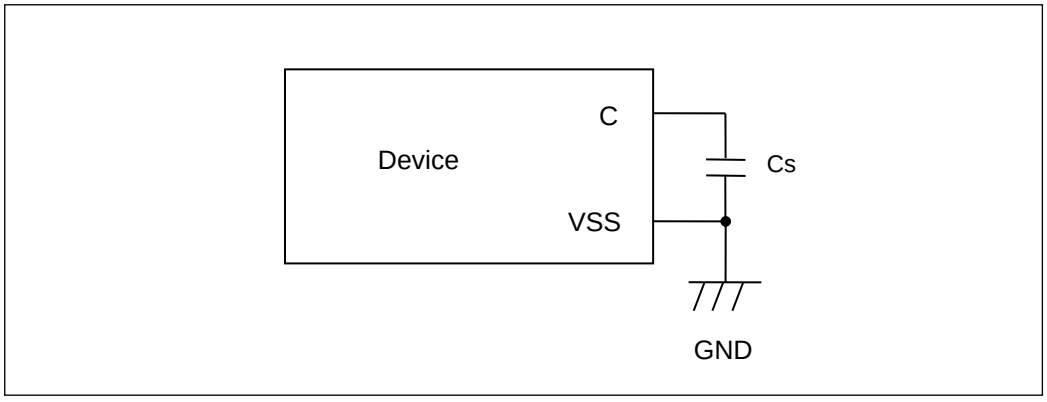
   Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
5. Smoke, Flame

   CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

C Pin

This series contains the regulator. Be sure to connect a smoothing capacitor (CS) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor.
However, some laminated ceramic capacitors have the characteristics of capacitance variation due to thermal fluctuation (F characteristics and Y5V characteristics). Please select the capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of a capacitor.
A smoothing capacitor of about 4.7µF would be recommended for this series.



Mode pins (MD0, MD1)

Connect the MD pin (MD0, MD1) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, as well as the distance between the mode pins and VCC pins or VSS pins is as short as possible and the connection impedance is low, when the pins are pulled-up/down such as for switching the pin level and rewriting the Flash memory data. It is because of preventing the device erroneously switching to test mode due to noise.

Notes on power-on

Turn power on/off in the following order or at the same time.
If not using the A/D converter, connect AVCC = VCC and AVSS = VSS.

Turning on: VCC → AVCC → AVRH

Turning off: AVRH → AVCC → VCC

Serial Communication

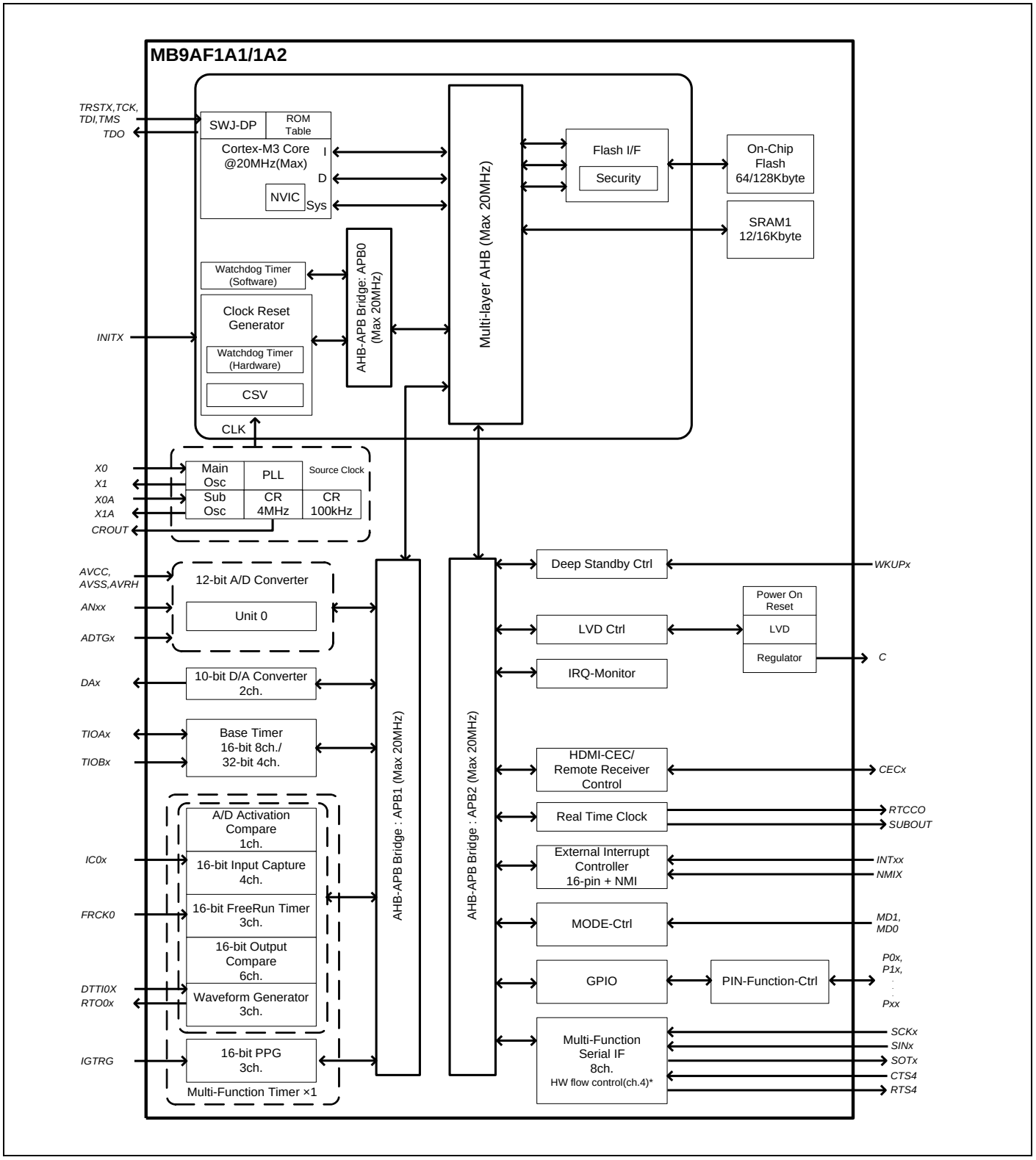
There is a possibility to receive wrong data due to the noise or other causes on the serial communication.
Therefore, design a printed circuit board so as to avoid noise.
Consider the case of receiving wrong data due to noise, perform error detection such as by applying a checksum of data at the end.
If an error is detected, retransmit the data.

Differences in features among the products with different memory sizes and between Flash memory products and MASK products

The electric characteristics including power consumption, ESD, latch-up, noise characteristics, and oscillation characteristics among the products with different memory sizes and between Flash memory products and MASK products are different because chip layout and memory structures are different.

If you are switching to use a different product of the same series, please make sure to evaluate the electric characteristics.

8. Block Diagram



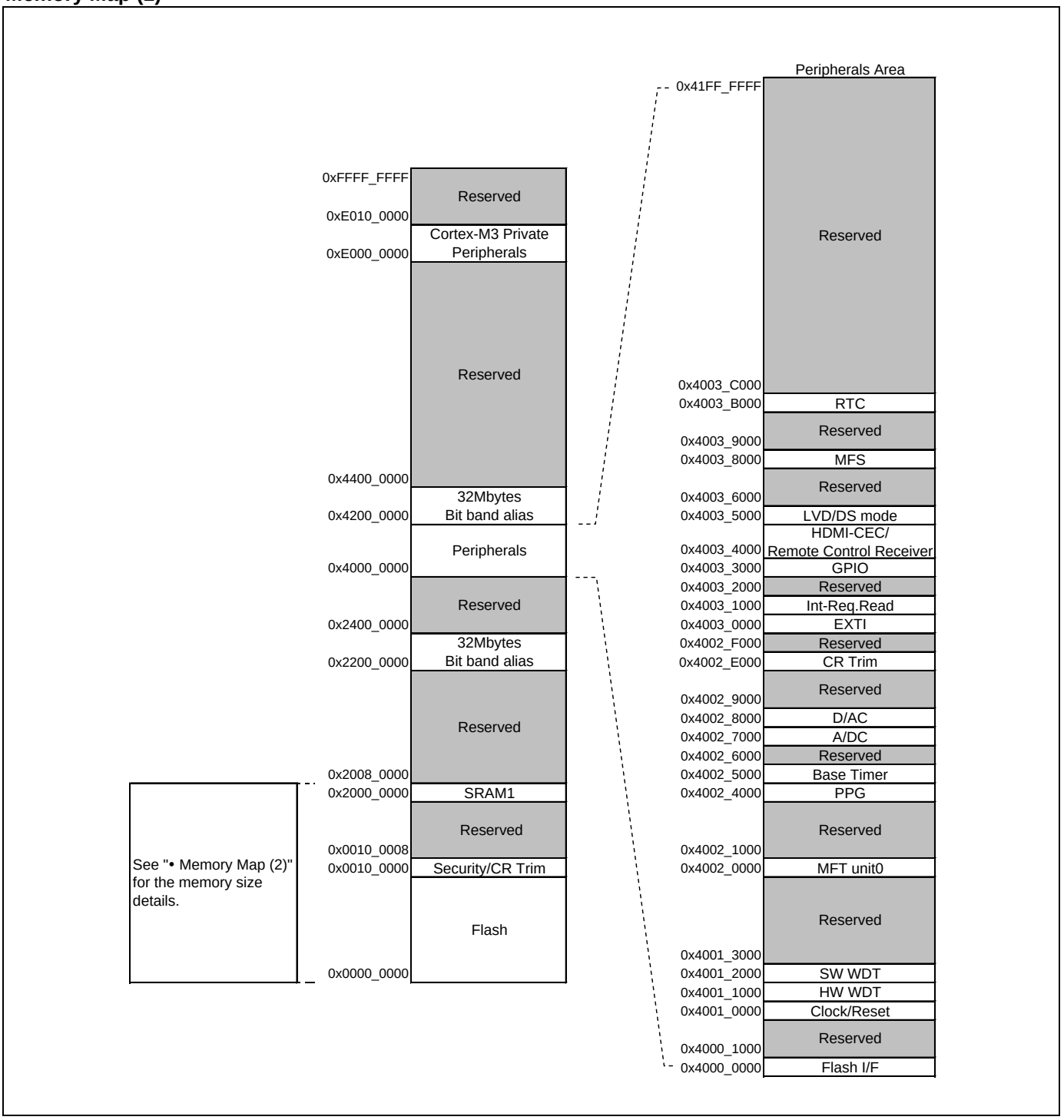
*: For the MB9AF1A1L and MB9AF1A2L, Multi-function Serial Interface does not support hardware flow control in these products.

9. Memory Size

See Memory size in Product Lineup to confirm the memory size.

10. Memory Map

Memory Map (1)



Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
H	Resource selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected							Output maintains previous state / Internal input fixed at 0		Maintain previous state
I	NMIX selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at 0			
	GPIO selected									Maintain previous state
J	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	Resource other than above selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected							Output maintains previous state / Internal input fixed at 0		Maintain previous state

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
K	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	External interrupt enabled selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	GPIO selected
	Resource other than above selected						Hi-Z / Internal input fixed at 0			
	GPIO selected							Output maintains previous state / Internal input fixed at 0		Maintain previous state
L	Analog input selected	Hi-Z	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled	Hi-Z / Internal input fixed at 0 / Analog input enabled
	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	External interrupt enabled selected						Maintain previous state	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	
	Resource other than above selected						Hi-Z / Internal input fixed at 0			
	GPIO selected							Output maintains previous state / Internal input fixed at "0"		Maintain previous state

Pin status type	Function group	Power-on reset or low-voltage detection state	INITX input state	Device internal reset state	Run mode or Sleep mode state	Timer mode, RTC mode, or Stop mode state		Deep Standby RTC mode or Deep Standby Stop mode state		Return from Deep Standby mode state
		Power supply unstable	Power supply stable		Power supply stable	Power supply stable		Power supply stable		Power supply stable
		-	INITX = 0	INITX = 1	INITX = 1	INITX = 1		INITX = 1		INITX = 1
		-	-	-	-	SPL = 0	SPL = 1	SPL = 0	SPL = 1	-
P	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / input enabled	Maintain previous state	Hi-Z / input enabled	Maintain previous state
Q	CEC enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	GPIO selected
	GPIO selected							Output maintains previous state / Internal input fixed at 0		Maintain previous state
R	CEC enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z / Internal input fixed at 0	WKUP input enabled	Hi-Z / WKUP input enabled	GPIO selected
	External interrupt enabled selected						Maintain previous state	GPIO selected Internal input fixed at 0	Hi-Z / Internal input fixed at 0	
	Resource other than above selected	Hi-Z	Hi-Z / Input enabled	Hi-Z / Input enabled			Hi-Z / Internal input fixed at 0			
	GPIO selected							Output maintains previous state / Internal input fixed at 0		Maintain previous state

12. Electrical Characteristics

12.1 Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1,*2	V_{CC}	V_{SS} - 0.5	V_{SS} + 6.5	V	
Analog power supply voltage*1,*3	AV_{CC}	V_{SS} - 0.5	V_{SS} + 6.5	V	
Analog reference voltage*1,*3	AVRH	V_{SS} - 0.5	V_{SS} + 6.5	V	
Input voltage*1	V_I	V_{SS} - 0.5	V_{CC} + 0.5 (≤ 6.5 V)	V	
		V_{SS} - 0.5	V_{SS} + 6.5	V	5V tolerant
Analog pin input voltage*1	V_{IA}	V_{SS} - 0.5	AV_{CC} + 0.5 (≤ 6.5 V)	V	
Output voltage*1	V_O	V_{SS} - 0.5	V_{CC} + 0.5 (≤ 6.5 V)	V	
L level maximum output current*4	I_{OL}	-	10	mA	
L level average output current*5	I_{OLAV}	-	4	mA	
L level total maximum output current	$\sum I_{OL}$	-	100	mA	
L level total average output current*6	$\sum I_{OLAV}$	-	50	mA	
H level maximum output current*4	I_{OH}	-	- 10	mA	
H level average output current*5	I_{OHAV}	-	- 4	mA	
H level total maximum output current	$\sum I_{OH}$	-	- 100	mA	
H level total average output current*6	$\sum I_{OHAV}$	-	- 50	mA	
Power consumption	P_D	-	400	mW	
Storage temperature	T_{STG}	- 55	+ 150	°C	

*1: These parameters are based on the condition that $V_{SS} = AV_{SS} = 0$ V.
*2: V_{CC} must not drop below V_{SS} - 0.5 V.
*3: Be careful not to exceed V_{CC} + 0.5 V, for example, when the power is turned on.
*4: The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.
*5: The average output current is defined as the average current value flowing through any one of the corresponding pins for a 100 ms period.
*6: The total average output current is defined as the average current value flowing through all of corresponding pins for a 100 ms.

WARNING:

- *Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings.*
  Do not exceed any of these ratings.

12.2 Recommended Operating Conditions

(V_{SS} = AV_{SS} = 0.0V)

Parameter		Symbol	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply voltage		V_{CC}	-	1.8	5.5	V	
Analog power supply voltage		AV_{CC}	-	1.8	5.5	V	AV_{CC} = V_{CC}
Analog reference voltage		AVRH	-	2.7	AV_{CC}	V	AV_{CC} ≥ 2.7 V
				AV_{CC}			AV_{CC} < 2.7 V
Smoothing capacitor		C_S	-	1	10	µF	For built-in Regulator *
Operating Temperature	LQD064, LQG064, LQH080, LQJ080, LQI100, PQH100	T_A	-	- 40	+ 85	°C	

*: See C Pin in Handling Devices for the smoothing capacitor.

WARNING:

- *The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.*
  Any use of semiconductor devices will be under their recommended operating condition.
  Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.
  No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

12.4.11 I²C Timing

(V_{CC} = 1.8V to 5.5V, V_{SS} = 0V, T_A = - 40°C to + 85°C)

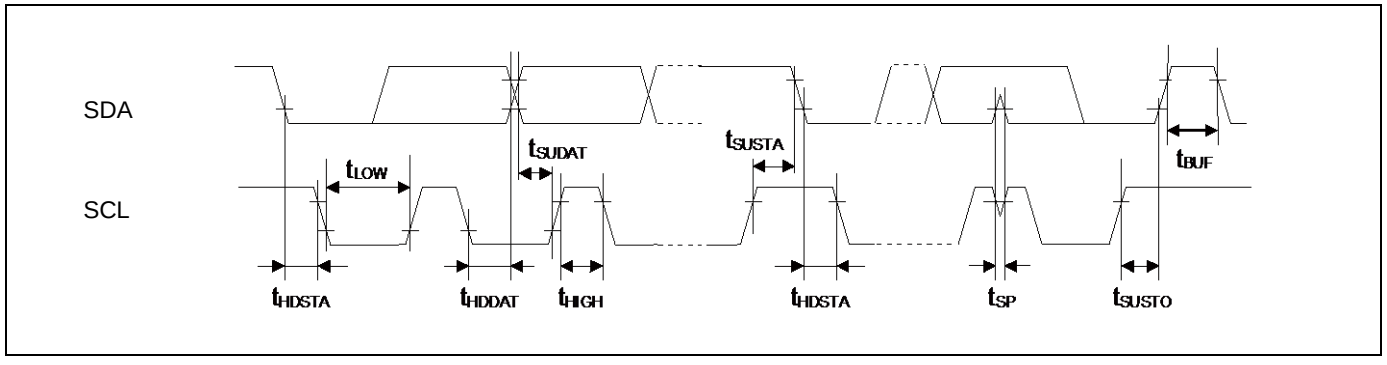
Parameter	Symbol	Conditions	Standard-mode		Fast-mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	f_{SCL}	C_L = 50 pF, R = (V_P/I_{OL})*1	0	100	0	400	kHz	
(Repeated) START condition hold time SDA ↓ → SCL ↓	t_{HDSTA}		4.0	-	0.6	-	µs	
SCL clock L width	t_{LOW}		4.7	-	1.3	-	µs	
SCL clock H width	t_{HIGH}		4.0	-	0.6	-	µs	
(Repeated) START condition setup time SCL ↑ → SDA ↓	t_{SUSTA}		4.7	-	0.6	-	µs	
Data hold time SCL ↓ → SDA ↓ ↑	t_{HDDAT}		0	3.45*2	0	0.9*3	µs	
Data setup time SDA ↓ ↑ → SCL ↑	t_{SUDAT}		250	-	100	-	ns	
STOP condition setup time SCL ↑ → SDA ↑	t_{SUSTO}		4.0	-	0.6	-	µs	
Bus free time between STOP condition and START condition	t_{BUF}		4.7	-	1.3	-	µs	
Noise filter	t_{SP}	-	2 t_{CYCP}*4	-	2 t_{CYCP}*4	-	ns	

*1: R and C_L represent the pull-up resistor and load capacitance of the SCL and SDA lines, respectively.
V_P indicates the power supply voltage of the pull-up resistor and I_{OL} indicates V_{OL} guaranteed current.

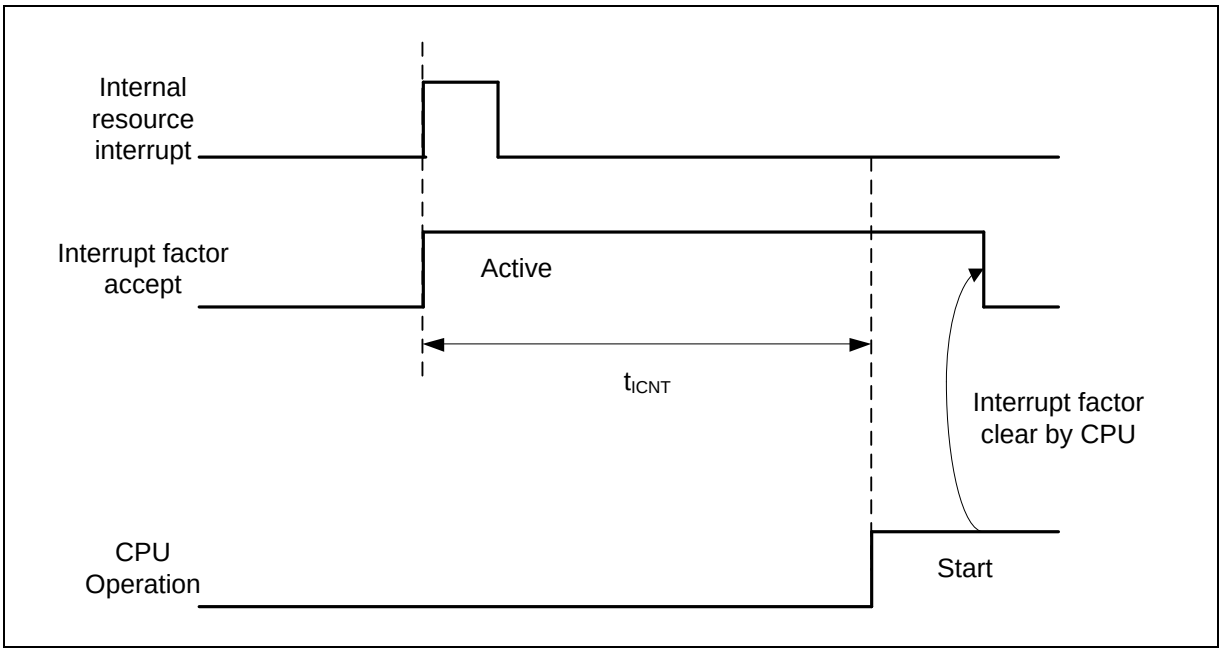
*2: The maximum t_{HDDAT} must satisfy that it does not extend at least L period (t_{LOW}) of device's SCL signal.

*3: A Fast-mode I²C bus device can be used on a Standard-mode I²C bus system as long as the device satisfies the requirement of t_{SUDAT} ≥ 250 ns.

*4: t_{CYCP} is the APB bus clock cycle time.
About the APB bus number which I²C is connected to, see Block Diagram in this data sheet.
To use Standard-mode, set the APB bus clock at 2 MHz or more.
To use Fast-mode, set the APB bus clock at 8 MHz or more.



Operation example of return from Low-Power consumption mode (by internal resource interrupt*)

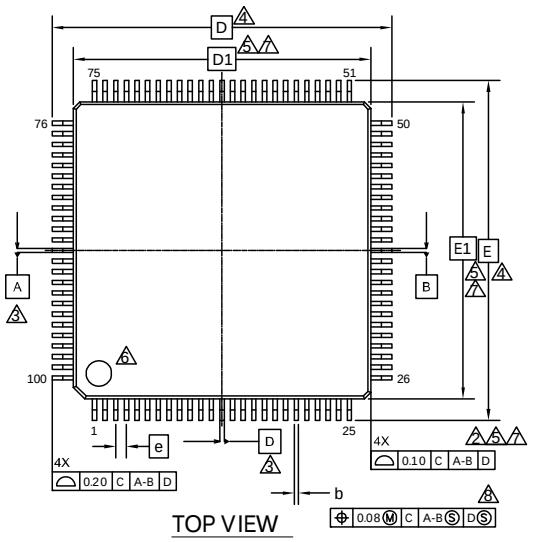


*: Internal resource interrupt is not included in return factor by the kind of Low-Power consumption mode.

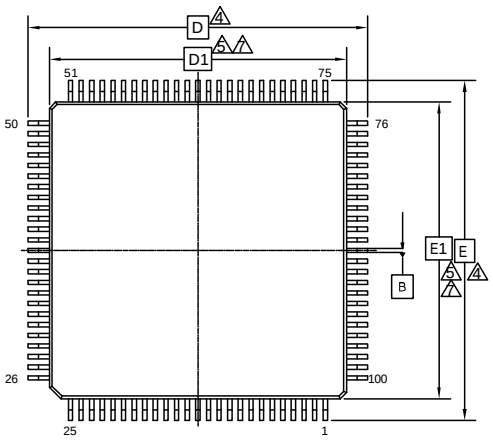
Notes:

- *The return factor is different in each Low-Power consumption modes. See Chapter 6: Low Power Consumption Mode and Operations of Standby Modes in FM3 Family Peripheral Manual.*
- *When interrupt recoveries, the operation mode that CPU recoveries depend on the state before the Low-Power consumption mode transition. See Chapter 6: Low Power Consumption Mode in FM3 Family Peripheral Manual.*

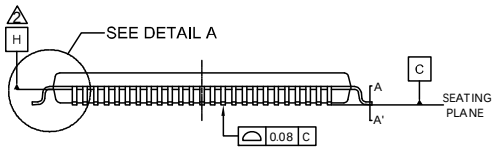
Package Type	Package Code
LQFP 100	LQI100



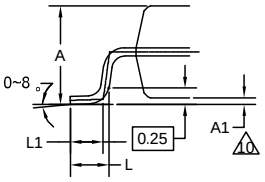
TOP VIEW



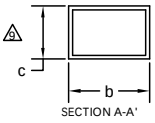
BOTTOM VIEW



SIDE VIEW



DETAIL A



SECTION A-A'

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.15	—	0.27
c	0.09	—	0.20
D	16.00 BSC		
D1	14.00 BSC		
e	0.50 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70

NOTES :

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-11500 **

PACKAGE OUTLINE, 100 LEAD LQFP
14.0X14.0X1.7 MM LQI100 Rev**

Document History

Document Title: MB9A1A0N Series 32-bit ARM® Cortex®-M3 FM3 Microcontroller
Document Number: 002-05675

<table>
<tr><th>Revision</th><th>ECN</th><th>Orig. of Change</th><th>Submission Date</th><th>Description of Change</th></tr>
<tr><td>**</td><td>-</td><td>AKIH</td><td>06/30/2015</td><td>Migrated to Cypress and assigned document number 002-05675.
No change to document contents or format.</td></tr>
<tr><td>*A</td><td>5193131</td><td>AKIH</td><td>03/31/2016</td><td>Updated to Cypress format.</td></tr>
<tr><td>*B</td><td>5513616</td><td>HTER</td><td>02/08/2017</td><td>Modified RTC description in “Features, Real-Time Clock(RTC)”. Changed starting count value from 01 to 00. Deleted “second, or day of the week” in the Interrupt function. (Page 2)
Changed package code as the following table in following section.
2. Package (Page 7)
3. Pin Assignment (Page 8 -11)
12. Electrical Characteristics (Page 53)
13. Ordering Information (Page 87)
14. Package Dimensions (Page 88 - 93)
<table>
<tr><th>Before</th><th>After</th></tr>
<tr><td>FPT-64P-M38</td><td>LQD064</td></tr>
<tr><td>FPT-64P-M39</td><td>LQG064</td></tr>
<tr><td>FPT-80P-M37</td><td>LQH080</td></tr>
<tr><td>FPT-80P-M40</td><td>LQJ080</td></tr>
<tr><td>FPT-100P-M23</td><td>LQI100</td></tr>
<tr><td>FPT-100P-M06</td><td>PQH100</td></tr>
</table>
Added the Baud rate spec in “12.4.9 CSIO/UART Timing” (Page 64 - 70)
Changed Part numbers in 13. Ordering Information (Page 87)
“MB9AF1A2LPMC-G-SNE2” to “MB9AF1A2LPMC-G-UNE2”
“MB9AF1A2MPMC-G-SNE2” to “MB9AF1A2MPMC-G-UNE2”
“MB9AF1A2NPMC-G-SNE2” to “MB9AF1A2NPMC-G-UNE2”
“MB9AF1A1MPMC-G-SNE2” to “MB9AF1A1MPMC-G-UNE2”
“MB9AF1A2MPMC1-G-SNE2” to “MB9AF1A2MPMC1-G-UNE2”
Added 15. Errata (Page 94 - 95)</td></tr>
</table>

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